

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10632552			
<b>Filing Date:</b>	02-Aug-2003			
<b>Title of Invention:</b>	Semiconductor multi-package module having package stacked over die-up flip chip ball grid array package and having wire bond interconnect between stacked packages			
<b>First Named Inventor:</b>	Marcos Karnezos			
<b>Filer:</b>	Bill Kennedy/Paula Hurley			
<b>Attorney Docket Number:</b>	CPAC 1017-5			
Filed as Large Entity				
<b>Utility      Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Notice of appeal	1401	1	500	500
Post-Allowance-and-Post-Issuance:				
<b>Extension-of-Time:</b>				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
Total in USD (\$)				680